Supporting Information

New Sulphur Bridged Neutral Annulenes. Structure, Physical Properties and Application in Organic Field-Effect Transistors

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Materials and Methods

The solvents and reagents: diethyl ether/hexane/tetrahydrofuran (THF) (Nabenzophenone ketyl), dichloromethane (DCM)/acetophenone/alkyl halides (CaCl₂), acetone (K₂CO₃), diisopropylamine/pyridine (KOH pellets), dimethylformamide (molecular sieves) were adequately dried as specified and drawn under N₂ atmosphere using hypodermic glass syringes. Titanium tetrachloride (TiCl₄) was distilled before use. Low boiling reagents were invariably distilled over 4Å molecular sieves. Freshly prepared *n*-BuLi (2.1 N in hexane) was titrated against diphenylacetic acid¹ before use. Reactions were run under a blanket of dry nitrogen gas in round-bottomed flasks, sealed with rubber septum (Aldrich). Organometallic reagents were transferred using cannula. The low temperature (0°C) was achieved by using ice-flakes.

Synthesis of 5,16-dihydro tetrathia[20]annulene 9 derivatives

To a suspension of zinc dust (54.15 mmol) in dry THF (200 ml) was added TiCl₄ (27 mmol, 1M in DCM) under nitrogen with stirring over 30 min. The reaction mixture was refluxed for 1 h, and then a solution of appropriate dialdehyde **8** (2.61 mmol) (Scheme 1, manuscript) and pyridine (43.57 mmol) in 200 ml of anhydrous THF was added through a cannula over 45 min to the gently refluxing suspension. After refluxing under nitrogen for 16 h, the dark reaction mixture was cooled to room temperature and quenched with aqueous K_2CO_3 (10%, 50 ml). The resulting mixture was filtered through Celite. Filtrate was washed with water, dried with Na₂SO₄, filtered and the solvent evaporated under reduced pressure. The corresponding products **9** were purified by flash chromatography using silica gel-G (60-120 mesh) and mixtures of ethyl acetate/hexane as eluent. The following products have been prepared.

5,16-Diphenyl-5,16-dihydrotetrathia[20]annulene (9a)

Yield 74%; Light green solid; m.p. 208-210°C (DCM); (Found C, 73.05; H, 4.06; S, 22.68. $C_{34}H_{24}S_4$ requires C, 72.85; H, 4.28; S, 22.85%); v_{max} (KBr)/cm⁻¹ 3030 and 1630; $\delta_{\rm H}$ (300 MHz, CDCl₃; Me₄Si) 5.74 (2H, s, *meso*-CH), 6.48-6.49 (4H, m, 4 x CH), 6.60-6.65 (4H, m, 4 x CH), 6.80-6.82 (4H, m, 4 x CH), 7.24-7.26 (2H, m, ArH), 7.27-7.33 (8H, m, ArH); $\delta_{\rm C}$ (75 MHz, CDCl₃; Me₄Si) 48.2, 123.5, 125.6, 127.0, 128.4, 128.5, 128.5, 138.5, 142.8 and 149.1; *m/z* (FAB) 561 (M⁺+1).

5,16-Bis(*p*-tolyl)-5,16-dihydrotetrathia[20]annulene (9b)

Yield 82%; Light green solid; m.p. 214-216 °C (DCM); (Found: C, 73.56; H, 4.56; S, 21.89. $C_{36}H_{28}S_4$ requires C, 73.47; H, 4.76; S, 21.77%); v_{max} (KBr)/cm⁻¹ 2170 and 1490; δ_H (300 MHz, CDCl₃; Me₄Si) 2.36 (6H, s, 2 x Me), 5.74 (2H, s, *meso*-CH), 6.49-6.59 (4H, m, CH), 6.60-6.64 (4H, m, ArH), 6.80-6.82 (4H, m, ArH), 7.22-7.31 (8H, m, ArH). δ_C (75 MHz, CDCl₃; Me₄Si) 21.4, 48.3, 48.4, 123.7, 123.8, 125.8, 128.7, 128.7, 128.8, 128.9, 137.1, 138.8, 140.3, 140.5, 149.7 and 149.8; *m/z* (FAB) 589 (M⁺+1).

5,16-Bis(4-chlorophenyl)-5,16-dihydrotetrathia[20]annulene (9c)

Yield 78%; Light green solid; m.p. 218-220 °C (DCM); (Found: C, 65.09; H, 3.42; S, 20.56. $C_{34}H_{22}S_4Cl_2$ requires C, 64.86; H, 3.50; S, 20.35%); v_{max} (KBr)/cm⁻¹ 2277 and 1530; δ_H (300 MHz, CDCl₃; Me₄Si) 5.73 (1H, s, *meso*-CH), 5.75 (1H, s, *meso*-CH), 6.65 (4H, s, CH), 6.60-6.67 (4H, m, ArH), 6.83 (4H, s, ArH), 7.14-7.28 (8H, m, ArH); δ_C (75 MHz, CDCl₃; Me₄Si) 47.5, 113.8, 123.3, 123.4, 125.4, 128.4, 128.5, 129.4, 129.5, 138.4, 149.5 and 149.6; *m/z* (FAB) 630 (M⁺+1).

Synthesis of 5,16-diphenyltetrathia[22]annulene derivatives 10a-c

To a clear solution of appropriate 5,16-dihydrotetrathia[20]annulene 9 (0.89 mmol) in anhydrous toluene (20 ml), was added a solution of DDQ (1.05 mmol) in anhydrous toluene (10 ml). Upon mixing the two solutions, a black precipitates formed immediately. The mixture was stirred for 2 hrs. The black precipitates were filtered and added to 10 ml of hydrazine (95%). After refluxing for 30 min. the mixture was cooled to room temperature, extracted with DCM, evaporated under reduced pressure, and the product was purified by flash chromatography using silica gel-G (60-120 mesh) and DCM as eluent. For preparing sample for micro-analytical analysis, recrystallization was done using combinations of anhydrous DCM and toluene.

5,16-Diphenyltetrathia[22]annulene (10a)

Yield 85%; Purple crystalline solid; m.p. 300° C (DCM); (Found: C, 73.33; H, 3.78; S, 22.78. C₃₄H₂₂S₄ requires C, 73.11; H, 3.94; S, 22.94%); ν_{max} (KBr)/cm⁻¹ 3050, 1620 and 1580; $\delta_{\rm H}$ (400 MHz, CDCl₃; Me₄Si) 7.99 (6H,d, *J* 6.3, ArH), 8.46 (4H, s, ArH), 10.01 (4H, d, *J* 5.2, 4 x CH), 10.40 (4H, d, *J* 4.5, 4 x CH), 11.09 (4H, s, 4 x

CH). δ_C (100 MHz, CDCl₃+TFA) 121.5, 128.2, 128.6, 128.8, 129.2, 131.7, 132.7, 135.2, 135.7, 136.9, 142.3 and 148.3. *m/z* (FAB) 559 (M⁺+1).

5,16-Bis(p-tolyl)tetrathia[22]annulene (10b)

Yield 80%. Purple crystalline solid; m.p. 300 °C (DCM); (Found: C, 73.64; H, 4.72; S, 21.76. $C_{36}H_{26}S_4$ requires C, 73.72; H, 4.44; S, 21.84%); v_{max} (KBr)/cm⁻¹ 3590, 3000 and 1620. δ_{H} (400 MHz, CDCl_{3;} Me₄Si) 1.25 (6H, s, CH₃), 7.98 (3H, d, *J* 8.2, ArH), 8.40 (4H, d, *J* 7.8, ArH), 9.98 (5H, d, *J* 9.9, ArH), 10.40 (4H, d, *J* 4.8, ArH), 11.09 (4H, s, CH). *m/z* (FAB) 587 (M⁺+1).

5,16-Bis(4-chlorophenyl)tetrathia[22]annulene (10c)

Yield 82%; Purple crystalline solid; m.p. 300 °C (DCM); (Found: C, 65.32; H, 3.36; S, 20.72. $C_{34}H_{20}S_4Cl_2$ requires C, 65.07; H, 3.19; S, 20.41%); v_{max} (KBr)/cm⁻¹ 3590, 3000 and 1620. δ_H (300 MHz, CDCl₃, Me₄Si) 7.99 (4H, s, ArH), 8.41 (4H, d, *J* 3, ArH), 10.00 (4H, m, ArH), 10.42 (4H, s, ArH), 11.11 (4H, s, CH). *m/z* (FAB) 626 (M⁺-1).

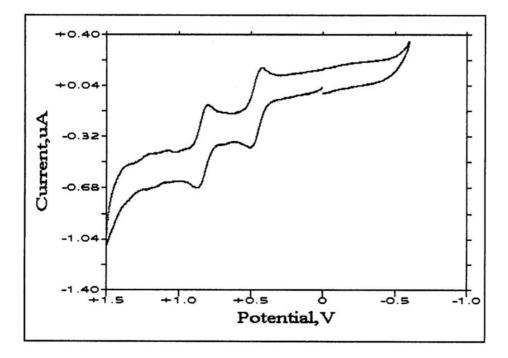


Figure S1. Cyclic voltammogram for **10b** (DCM, electrolyte tetrabutylammonium hexafluorophosphate; working electrode: Pt; reference electrode: Ag/AgCl; 80 mVs⁻¹.

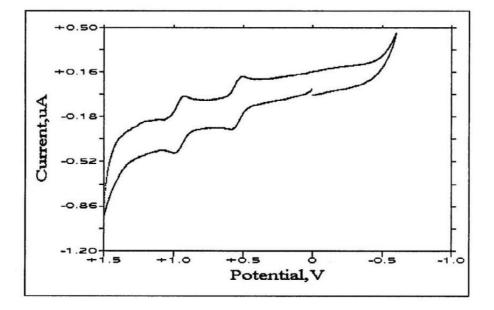


Figure S2. Cyclic voltammogram for **10c** (DCM, electrolyte tetrabutylammonium hexafluorophosphate; working electrode: Pt; reference electrode: Ag/AgCl; 80 mVs⁻¹.

Physical properties of thin films of 10a-c

The UV-vis absorption spectra of **10a-c** thin films are shown in Fig. S3.

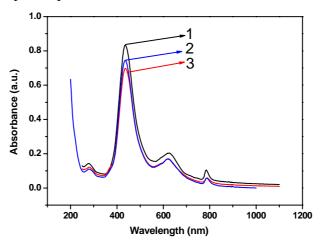


Fig. S3 Normalized UV-vis absorption spectra of 10a-c thin films at room temperature.

Film morphology

The morphology of 50 nm thick films of **10a-c** deposited on both plain SiO_2/Si and OTS-treated SiO_2/Si substrate at various substrate temperature were investigated by AFM (**Fig. S4**). When the substrate temperature was at room temperature (25 °C), the film deposited on SiO_2/Si substrate was made of small grains. When the substrate was treated with OTS at 25 °C, bigger and interconnected grains were observed and the film became more ordered. When the substrate temperature was increased to 60 °C, the grains became bigger and varied in shape for the film on both SiO_2/Si and $OTS/SiO_2/Si$ substrate. However, film discontinuity and large gaps increased as well. As the substrate temperature was increased to 100 °C, the film became cracked and lamellar crystalline grains were observed.

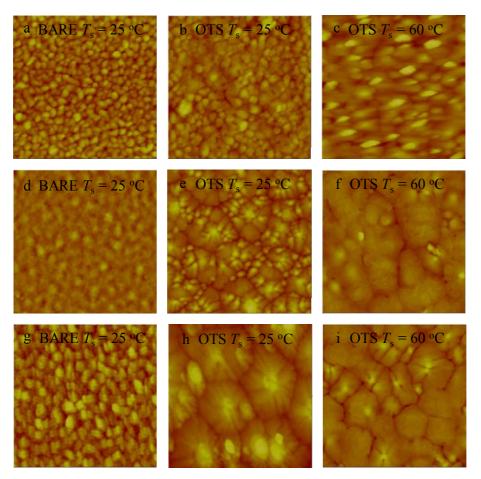


Fig. S4 AFM images (2 μ m× 2 μ m) of 50 nm thick films of **10a**: (a) deposited on SiO₂/Si substrate, $T_s = 25$ °C; (b) deposited on OTS/SiO₂/Si substrate, $T_s = 25$ °C; (c) deposited on OTS/SiO₂/Si substrate, $T_s = 60$ °C; **10b**: (d) deposited on SiO₂/Si substrate, $T_s = 25$ °C; (e) deposited on OTS/SiO₂/Si substrate, $T_s = 25$ °C; (f) deposited on OTS/SiO₂/Si substrate, $T_s = 25$ °C; (f) deposited on OTS/SiO₂/Si substrate, $T_s = 25$ °C; (f) deposited on OTS/SiO₂/Si substrate, $T_s = 25$ °C; (f) deposited on OTS/SiO₂/Si substrate, $T_s = 25$ °C; (f) deposited on OTS/SiO₂/Si substrate, $T_s = 25$ °C; (i) deposited on OTS/SiO₂/Si substrate, $T_s = 25$ °C; (j) deposited on OTS/SiO₂/Si substrate, $T_s = 25$ °C; (i) deposited on OTS/SiO₂/Si substrate, $T_s = 25$ °C; (j) deposited on OTS/SiO₂/Si substrate, $T_s = 25$ °C; (j) deposited on OTS/SiO₂/Si substrate, $T_s = 25$ °C; (j) deposited on OTS/SiO₂/Si substrate, $T_s = 25$ °C; (j) deposited on OTS/SiO₂/Si substrate, $T_s = 25$ °C; (j) deposited on OTS/SiO₂/Si substrate, $T_s = 25$ °C; (j) deposited on OTS/SiO₂/Si substrate, $T_s = 25$ °C; (j) deposited on OTS/SiO₂/Si substrate, $T_s = 25$ °C; (j) deposited on OTS/SiO₂/Si substrate, $T_s = 25$ °C; (j) deposited on OTS/SiO₂/Si substrate, $T_s = 60$ °C.

X-ray Diffraction

The X-ray diffraction patterns of the thin films of **10a-c** deposited on SiO₂/Si and OTS/SiO₂/Si substrate at various substrate temperatures (T_s) are shown in Fig. S5.

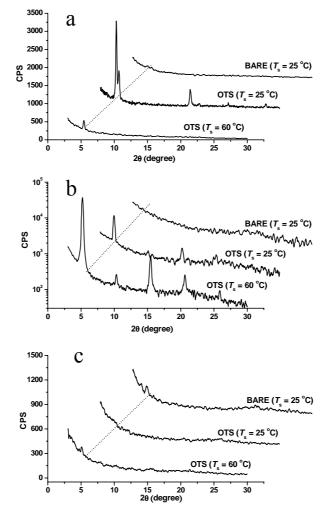


Fig. S5 X-Ray diffraction patterns of the thin films of (a) 10a, (b) 10b, (c) 10c deposited on SiO₂/Si and OTS/SiO₂/Si substrate at various substrate temperatures (T_s) .

FET characteristics

Top contact OFETs based on the thin films were fabricated. The results were summarized in Table 1. Here, the mobilities (μ) were calculated in the saturation regime by the following equation: $I_D = \mu C_i (W/2L) (V_G - V_T)^2$, where I_D is the drain current, μ is the field-effect mobility, C_i is the gate dielectric capacitance, W and L are the channel width and length, respectively, V_T is the threshold voltage. 2 exhibited the best OFET performance. When the SiO₂/Si substrate was treated with OTS, large improvement in the performance was observed, with the averange mobility increased

to 0.44 cm² V⁻¹ s⁻¹, the maximal mobility as high as 0.63 cm² V⁻¹ s⁻¹. The FET characteristics of **10a-c** are shown in Fig. S7.

$T_{\rm s}$ =25 °C	$\mu (\mathrm{cm}^2\mathrm{V}^{-1}\mathrm{s}^{-1})$	$I_{\rm on}/I_{\rm off}$	$V_{\mathrm{T}}\left(\mathrm{V} ight)$
10a-BARE	1.07×10 ⁻⁴	4.05	113
10a- OTS	0.25(0.29)	1.34×10 ³	-12.9
10b-BARE	2.03×10 ⁻⁵	52.7	40.6
10b- OTS	0.44(0.63)	3×10 ²	-7.47
10c-BARE	3.01×10 ⁻⁵	1.54×10 ³	1.33
10c- OTS	5.04×10 ⁻³ (9.68×10 ⁻³)	8.96×10 ⁵	-49.0
$T_{\rm s}$ =60 °C	$\mu ({\rm cm}^2{\rm V}^{-1}{\rm s}^{-1})$	$I_{\rm on}/I_{\rm off}$	$V_{\mathrm{T}}\left(\mathrm{V} ight)$
10a-BARE	3.20×10 ⁻⁴	12.1	56.5
10a- OTS	1.58×10 ⁻²	1.48×10 ³	-5.11
10b-BARE	2.03×10 ⁻⁴	4.22	90.5
10b- OTS	0.28(0.31)	1.34×10 ³	-17.6
10c-BARE	5.22×10 ⁻⁵	7.19×10 ³	28.7
10c- OTS	2.45×10 ⁻² (3.16×10 ⁻²)	3.03×10 ⁴	-50.1

 Table S1. Detailed performance of OFETs based on 10a-c thin films.

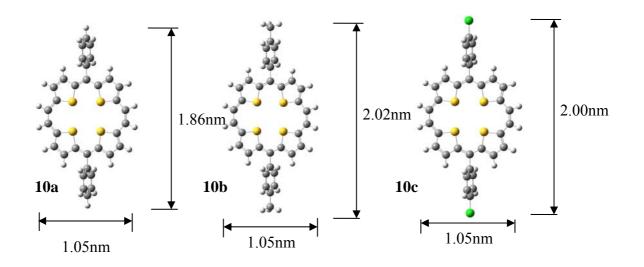


Figure S6.

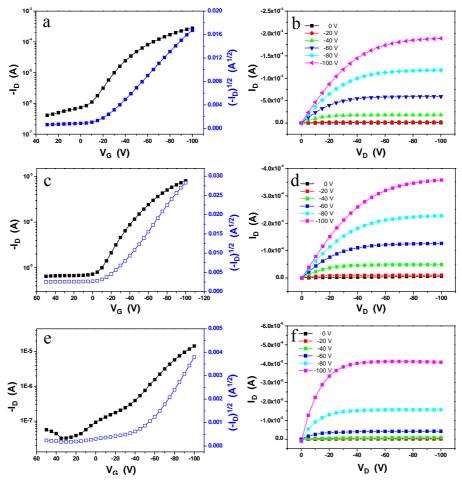


Fig. S7 Typical transfer (a) and output (b) characteristics of FET devices based on 10a, with OTS-treated SiO₂/Si substrate ($T_s = 25$ °C). Typical transfer (c) and output (d) characteristics of FET devices based on 10b, with OTS-treated SiO₂/Si substrate ($T_s = 25$ °C). Typical transfer (e) and output (f) characteristics of FET devices based on 10c, with OTS-treated SiO₂/Si substrate ($T_s = 60$ °C).

Experimental:

OFET devices were fabricated in the top-contact device configuration. The substrate was heavily doped, n-type Si gate electrode with a 500 nm thick SiO₂ layer as the gate dielectric. The gate dielectric was treated with octadecyltrichlorosilane (OTS) by vapor deposition method. Subsequently, organic semiconductors were deposited on the substrate by thermal evaporation under a pressure of 8×10^{-4} Pa at a deposition rate gradually increased from 0.1 Å s⁻¹ to 0.4 Å s⁻¹ at the first 20 nm and then maintained 0.5 Å s⁻¹ until the thickness of the film was 50 nm. The deposition rate and film thickness were monitored by a quartz crystal microbalance (ULVAC CRTM-6000). Finally, 20 nm thick gold source and drain electrode were deposited

through a shadow mask. The channel length (*L*) and width (*W*) were 0.11 mm and 5.30 mm, respectively. The FET characteristics were measured at room temperature in air using Keithley 4200 SCS. X-ray diffraction (XRD) measurements were carried out in the reflection mode at RT using a 2-kW Rigaku X-ray diffractometer (Cu K α radiation, $\lambda = 1.54$ Å). Atomic force microscopy (AFM) measurements were carried out with a Nanoscope IIIa instrument (Digital Instruments) operating in tapping mode. UV-Vis spectra were recorded on a JASCO V-570 spectrometer.

Reference

1. W. G. Kofron and L. M. Baclawski, J. Org. Chem. 1976, 41, 1879.